

W681512

SINGLE-CHANNEL VOICEBAND CODEC

Data Sheet Revision C17

1. GENERAL DESCRIPTION

The W681512 is a general-purpose single channel PCM CODEC with pin-selectable μ -Law or A-Law companding. The device is compliant with the ITU G.712 specification. It operates from a single +5V power supply and is available in 20-pin SOG (SOP), SSOP and TSSOP package. Functions performed include digitization and reconstruction of voice signals, and band limiting and smoothing filters required for PCM systems. The filters are compliant with ITU G.712 specification. W681512 performance is specified over the industrial temperature range of -40°C to +85°C.

The W681512 includes an on-chip precision voltage reference and an additional power amplifier, capable of driving 300Ω loads differentially up to a level of 6.3V peak-to-peak. The analog section is fully differential, reducing noise and improving the power supply rejection ratio. The data transfer protocol supports both long-frame and short-frame synchronous communications for PCM applications, and IDL and GCI communications for ISDN applications. W681512 accepts seven master clock rates between 256 kHz and 4.096 MHz, and an on-chip pre-scaler automatically determines the division ratio for the required internal clock.

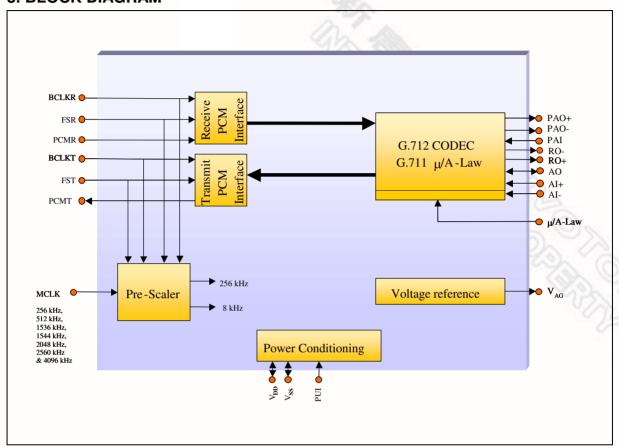
2. FEATURES

- Single +5V power supply
- Typical power dissipation of 30 mW, power-down mode of 0.5 μW
- Fully-differential analog circuit design and output signals
- Differential Analog Outputs
- On-chip precision reference of 1.575 V for a 0 dBm TLP at 600 Ω (775mV_{BMS})
- Push-pull power amplifiers with external gain adjustment with 300 Ω load capability
- Seven master clock rates of 256 kHz to 4.096 MHz
- Pin-selectable μ-Law and A-Law companding (compliant with ITU G.711)
- CODEC A/D and D/A filtering compliant with ITU G.712
- Industrial temperature range (-40°C to +85°C)
- Pb-Free Packages: 20-pin SOG (SOP), SSOP and TSSOP

Applications

- VoIP, Voice over Networks equipment
- Digital telephone and communication systems
- Wireless Voice devices
- DECT/Digital Cordless phones
- Broadband Access Equipment
- Bluetooth Headsets
- Fiber-to-curb equipment
- Enterprise phones
- Digital Voice Recorders

3. BLOCK DIAGRAM

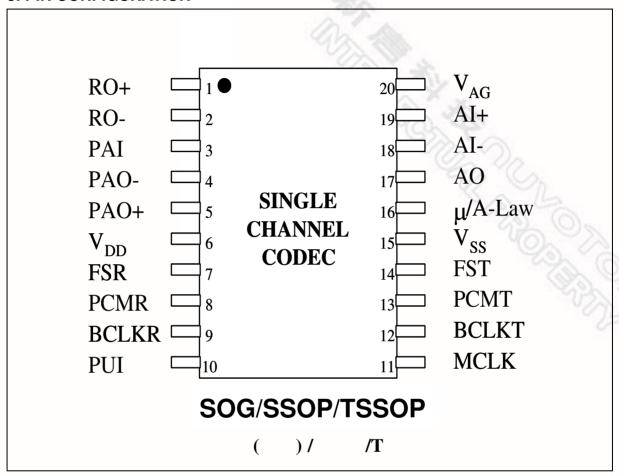


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5. PIN CONFIGURATION





6. PIN DESCRIPTION

Pin Name	Pin No.	Functionality
RO+	1	Non-inverting output of the receive smoothing filter. This pin can typically drive a 2 k Ω load to 1.575 volt peak referenced to the analog ground level.
RO-	2	Inverting output of the receive smoothing filter. This pin can typically drive a 2 k Ω load to 1.575 volt peak referenced to the analog ground level.
PAI	3	This pin is the inverting input to the power amplifier. Its DC level is at the V_{AG} voltage.
PAO-	4	Inverting power amplifier output. This pin can drive a 300 Ω load to 1.575 volt peak referenced to the V_{AG} voltage level.
PAO+	5	Non-inverting power amplifier output. This pin can drive a 300 Ω load to 1.575 volt peak referenced to the V_{AG} voltage level.
V_{DD}	6	Power supply. This pin should be decoupled to V _{SS} with a 0.1μF ceramic capacitor.
FSR	7	8 kHz Frame Sync input for the PCM receive section. This pin also selects channel 0 or channel 1 in the GCI and IDL modes. It can also be connected to the FST pin when transmit and receive are synchronous operations.
PCMR	8	PCM input data receive pin. The data needs to be synchronous with the FSR and BCLKR pins.
BCLKR	9	PCM receive bit clock input pin. This pin also selects the interface mode. The GCI mode is selected when this pin is tied to V_{SS} . The IDL mode is selected when this pin is tied to V_{DD} . This pin can also be tied to the BCLKT when transmit and receive are synchronous operations.
PUI	10	Power up input signal. When this pin is tied to V_{DD} , the part is powered up. When tied to V_{SS} , the part is powered down.
MCLK	11	System master clock input. Possible input frequencies are 256 kHz, 512 kHz, 1536 kHz, 1544 kHz, 2048 kHz, 2560 kHz & 4096 kHz. For a better performance, it is recommended to have the MCLK signal synchronous and aligned to the FST signal. This is a requirement in the case of 256 and 512 kHz frequency.
BCLKT	12	PCM transmit bit clock input pin.
PCMT	13	PCM output data transmit pin. The output data is synchronous with the FST and BCLKT pins.
FST	14	8 kHz transmit frame sync input. This pin synchronizes the transmit data bytes.
V_{SS}	15	This is the supply ground. This pin should be connected to 0V.
μ/A-Law	16	Compander mode select pin. μ -Law companding is selected when this pin is tied to V_{DD} . A-Law companding is selected when this pin is tied to V_{SS} .
AO	17	Analog output of the first gain stage in the transmit path.
Al-	18	Inverting input of the first gain stage in the transmit path.
Al+	19	Non-inverting input of the first gain stage in the transmit path.
V_{AG}	20	Mid-Supply analog ground pin, which supplies a 2.4 Volt reference voltage for all-analog signal processing. This pin should be decoupled to V_{SS} with a 0.01 μ F to 0.1 μ F capacitor. This pin becomes high impedance when the chip is powered down.

7. FUNCTIONAL DESCRIPTION

W681512 is a single-rail, single channel PCM CODEC for voiceband applications. The CODEC complies with the specifications of the ITU-T G.712 recommendation. The CODEC also includes a complete μ -Law and A-Law compander. The μ -Law and A-Law companders are designed to comply with the specifications of the ITU-T G.711 recommendation.

The block diagram in section 3 shows the main components of the W681512. The chip consists of a PCM interface, which can process long and short frame sync formats, as well as GCI and IDL formats. The pre-scaler of the chip provides the internal clock signals and synchronizes the CODEC sample rate with the external frame sync frequency. The power conditioning block provides the internal power supply for the digital and the analog section, while the voltage reference block provides a precision analog ground voltage for the analog signal processing. The main CODEC block diagram is shown in section 3.

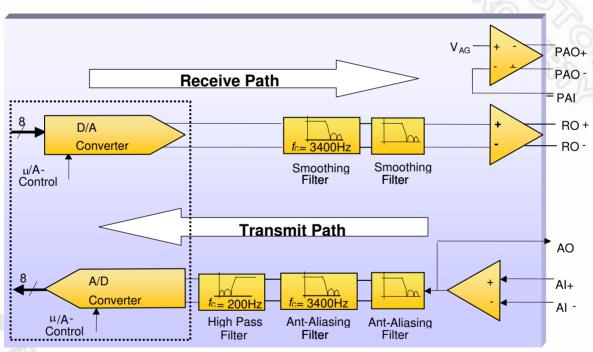


Figure 7.1 The W681512 Signal Path

7.1. Transmit Path

The A-to-D path of the CODEC contains an analog input amplifier with externally configurable gain setting (see application examples in section 11). The device has an input operational amplifier whose output is the input to the encoder section. If the input amplifier is not required for operation it can be powered down and bypassed. In that case a single ended input signal can be applied to the AO pin or the AI- pin. The AO pin becomes high input impedance when the input amplifier is powered down. The input amplifier can be powered down by connecting the AI+ pin to V_{DD} or V_{SS} . The AO pin is selected

as an input when AI+ is tied to V_{DD} and the AI- pin is selected as an input when AI+ is tied to V_{SS} (see Table 7.1).

Al+	Input Amplifier	Input
V _{DD}	Powered Down	AO
1.2 to V _{DD} -1.2	Powered Up	Al+, Al-
V _{SS}	Powered Down	Al-

Table 7.1 Input Amplifier Modes of operation

When the input amplifier is powered down, the input signal at AO or AI- needs to be referenced to the analog ground voltage V_{AG} .

The output of the input amplifier is fed through a low-pass filter to prevent aliasing at the switched capacitor 3.4 kHz low pass filter. The 3.4 kHz switched capacitor low pass filter prevents aliasing of input signals above 4 kHz, due to the sampling at 8 kHz. The output of the 3.4 kHz low pass filter is filtered by a high pass filter with a 200 Hz cut-off frequency. The filters are designed according to the recommendations in the G.712 ITU-T specification. From the output of the high pass filter the signal is digitized. The signal is converted into a compressed 8-bit digital representation with either μ -Law or A-Law format. The μ -Law or A-Law format is pin-selectable through the μ /A-Law pin. The compression format can be selected according to Table 7.2.

μ/A-Law Pin	Format
V_{SS}	A-Law
V_{DD}	μ-Law

Table 7.2. Pin-selectable Compression Format

The digital 8-bit μ -Law or A-Law samples are fed to the PCM interface for serial transmission at the data rate supplied by the external BCLKT.

7.2. Receive Path

The 8-bit digital input samples for the D-to-A path are serially shifted in by the PCM interface and converted to parallel data bits. During every cycle of the frame sync FSR, the parallel data bits are fed through the pin-selectable μ -Law or A-Law expander and converted to analog samples. The mode of expansion is selected by the μ /A-Law pin as shown in Table 7.2. The analog samples are filtered by a low-pass smoothing filter with a 3.4 kHz cut-off frequency, according to the ITU-T G.712 specification. A sin(x)/x compensation is integrated with the low pass smoothing filter. The output of this filter is buffered to provide the differential receive output signals RO+ and RO-. The RO+ or RO- outputs can be externally connected to the PAI pin to provide a differential output with high driving capability at the PAO+ and PAO- pins. By using external resistors (see section 11 for examples), various gain settings of this output amplifier can be achieved. If the transmit power amplifier is not in use, it can be powered down by connecting PAI to V_{DD} .

7.3. POWER MANAGEMENT

7.3.1. Analog and Digital Supply

The power supply for the analog and digital parts of the W681512 must be 5V +/- 10%. This supply voltage is connected to the V_{DD} pin. The V_{DD} pin needs to be decoupled to ground through a 0.1 μF ceramic capacitor.

7.3.2. Analog Ground Reference Voltage Output

The analog ground reference voltage is available for external reference at the V_{AG} pin. This voltage needs to be decoupled to V_{SS} through a 0.01 μF to a 0.1 μF ceramic capacitor.

7.4. PCM INTERFACE

The PCM interface is controlled by pins BCLKR, FSR, BCLKT & FST. The input data is received through the PCMR pin and the output data is transmitted through the PCMT pin. The modes of operation of the interface are shown in Table 7.3.

BCLKR	FSR	Interface Mode
64 kHz to 4.096 MHz	8 kHz	Long or Short Frame Sync
V _{SS}	V _{SS}	ISDN GCI with active channel B1
V _{SS}	V_{DD}	ISDN GCI with active channel B2
V _{DD}	V _{SS}	ISDN IDL with active channel B1
V_{DD}	V_{DD}	ISDN IDL with active channel B2

Table 7.3 PCM Interface mode selections

7.4.1. Long Frame Sync

The Long Frame Sync or Short Frame Sync interface mode can be selected by connecting the BCLKR or BCLKT pin to a 64 kHz to 4.096 MHz clock and connecting the FSR or FST pin to the 8 kHz frame sync. The device synchronizes the data word for the PCM interface and the CODEC sample rate on the positive edge of the Frame Sync signal. It recognizes a Long Frame Sync when the FST pin is held HIGH for two consecutive falling edges of the bit-clock at the BCLKT pin. The length of the Frame Sync pulse can vary from frame to frame, as long as the positive frame sync edge occurs every 125 µsec. During data transmission in the Long Frame Sync mode, the transmit data pin PCMT will become low impedance when the Frame Sync signal FST is HIGH or when the 8 bit data word is being transmitted. The transmit data pin PCMT will become high impedance when the Frame Sync signal FST becomes LOW while the data is transmitted or when half of the LSB is transmitted. The internal decision logic will determine whether the next frame sync is a long or a short frame sync, based on the previous frame sync pulse. To avoid bus collisions, the PCMT pin will be high impedance for two frame sync cycles after every power down state. More detailed timing information can be found in the interface timing section.

7.4.2. Short Frame Sync

The W681512 operates in the Short Frame Sync Mode when the Frame Sync signal at pin FST is HIGH for one and only one falling edge of the bit-clock at the BCLKT pin. On the following rising edge of the bit-clock, the W681512 starts clocking out the data on the PCMT pin, which will also change from high to low impedance state. The data transmit pin PCMT will go back to the high impedance state halfway through the LSB. The Short Frame Sync operation of the W681512 is based on an 8-bit data word. When receiving data on the PCMR pin, the data is clocked in on the first falling edge after the falling edge that coincides with the Frame Sync signal. The internal decision logic will determine whether the next frame sync is a long or a short frame sync, based on the previous frame sync pulse. To avoid bus collisions, the PCMT pin will be high impedance for two frame sync cycles after every power down state. More detailed timing information can be found in the interface timing section.

7.4.3. General Circuit Interface (GCI)

The GCI interface mode is selected when the BCLKR pin is connected to $V_{\rm SS}$ for two or more frame sync cycles. It can be used as a 2B+D timing interface in an ISDN application. The GCI interface consists of 4 pins: FSC (FST), DCL (BCLKT), Dout (PCMT) & Din (PCMR). The FSR pin selects channel B1 or B2 for transmit and receive. Data transitions occur on the positive edges of the data clock DCL. The Frame Sync positive edge is aligned with the positive edge of the data clock DCLK. The data rate is running half the speed of the bit-clock. The channels B1 and B2 are transmitted consecutively. Therefore, channel B1 is transmitted on the first 16 clock cycles of DCL and B2 is transmitted on the second 16 clock cycles of DCL. For more timing information, see the timing section.

7.4.4. Interchip Digital Link (IDL)

The IDL interface mode is selected when the BCLKR pin is connected to V_{DD} for two or more frame sync cycles. It can be used as a 2B+D timing interface in an ISDN application. The IDL interface consists of 4 pins: IDL SYNC (FST), IDL CLK (BCLKT), IDL TX (PCMT) & IDL RX (PCMR). The FSR pin selects channel B1 or B2 for transmit and receive. The data for channel B1 is transmitted on the first positive edge of the IDL CLK after the IDL SYNC pulse. The IDL SYNC pulse is one IDL CLK cycle long. The data for channel B2 is transmitted on the eleventh positive edge of the IDL CLK after the IDL SYNC pulse. The data for channel B1 is received on the first negative edge of the IDL CLK after the IDL SYNC pulse. The data for channel B2 is received on the eleventh negative edge of the IDL CLK after the IDL SYNC pulse. The transmit signal pin IDL TX becomes high impedance when not used for data transmission and also in the time slot of the unused channel. For more timing information, see the timing section.

7.4.5. System Timing

The system can work at 256 kHz, 512 kHz, 1536 kHz, 1544 kHz, 2048 kHz, 2560 kHz & 4096 kHz master clock rates. The system clock is supplied through the master clock input MCLK and can be derived from the bit-clock if desired. An internal pre-scaler is used to generate a fixed 256 kHz and 8 kHz sample clock for the internal CODEC. The pre-scaler measures the master clock frequency versus the Frame Sync frequency and sets the division ratio accordingly. If the Frame Sync is LOW for the entire frame sync period while the MCLK and BCLK pin clock signals are still present, the W681512 will enter the low power standby mode. Another way to power down is to set the PUI pin to LOW. When the system needs to be powered up again, the PUI pin needs to be set to HIGH and the Frame Sync pulse needs to be present. It will take two Frame Sync cycles before the pin PCMT will become low impedance.

8. TIMING DIAGRAMS

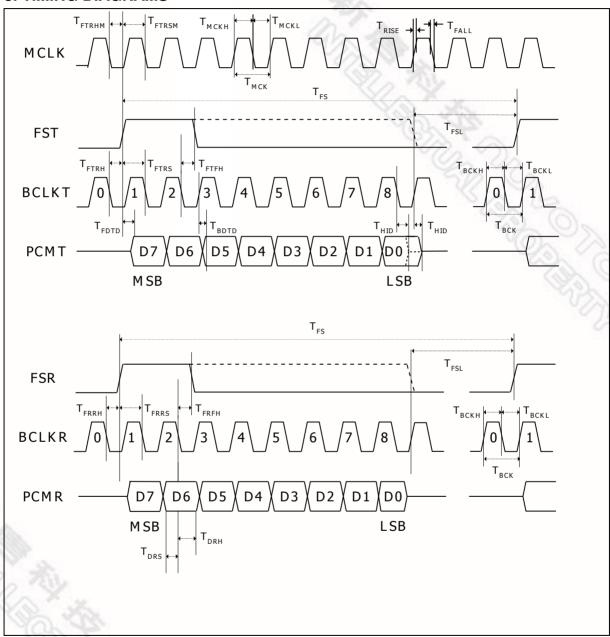


Figure 8.1 Long Frame Sync PCM Timing

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
1/T _{FS}	FST, FSR Frequency	A	8		kHz
T _{FSL}	FST / FSR Minimum LOW Width ¹	T _{BCK}	0		sec
1/T _{BCK}	BCLKT, BCLKR Frequency	64	J	4096	kHz
T _{BCKH}	BCLKT, BCLKR HIGH Pulse Width	50	SHE		ns
T _{BCKL}	BCLKT, BCLKR LOW Pulse Width	50	1 12		ns
T _{FTRH}	BCLKT 0 Falling Edge to FST Rising Edge Hold Time	20		D	ns
T _{FTRS}	FST Rising Edge to BCLKT 1 Falling edge Setup Time	80	76	3	ns
T _{FTFH}	BCLKT 2 Falling Edge to FST Falling Edge Hold Time	50		100	ns
T _{FDTD}	FST Rising Edge to Valid PCMT Delay Time			60	ns
T _{BDTD}	BCLKT Rising Edge to Valid PCMT Delay Time			60	ns
T _{HID}	Delay Time from the Later of FST Falling Edge, or	10		60	ns
	BCLKT 8 Falling Edge to PCMT Output High Impedance				
T _{FRRH}	BCLKR 0 Falling Edge to FSR Rising Edge Hold Time	20			ns
T _{FRRS}	FSR Rising Edge to BCLKR 1 Falling edge Setup Time	80			ns
T _{FRFH}	BCLKR 2 Falling Edge to FSR Falling Edge Hold Time	50			ns
T _{DRS}	Valid PCMR to BCLKR Falling Edge Setup Time	0			ns
T _{DRH}	PCMR Hold Time from BCLKR Falling Edge	50			ns

Table 8.1 Long Frame Sync PCM Timing Parameters

 $^{^{1}}$ T_{FSL} must be at least \geq T_{BCK}

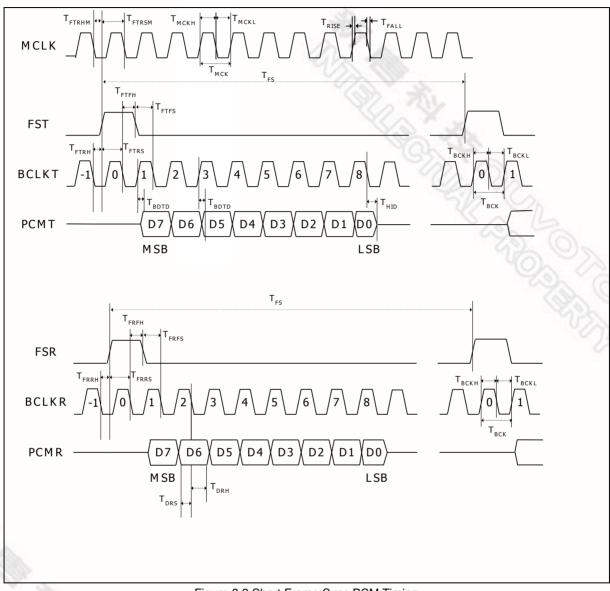
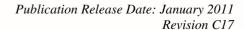


Figure 8.2 Short Frame Sync PCM Timing

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
1/T _{FS}	FST, FSR Frequency		8		kHz
1/T _{BCK}	BCLKT, BCLKR Frequency	64		4096	kHz
Твскн	BCLKT, BCLKR HIGH Pulse Width	50			ns
T _{BCKL}	BCLKT, BCLKR LOW Pulse Width	50			ns
T _{FTRH}	BCLKT –1 Falling Edge to FST Rising Edge Hold Time	20			ns
T _{FTRS}	FST Rising Edge to BCLKT 0 Falling edge Setup Time	80	((()		ns
T _{FTFH}	BCLKT 0 Falling Edge to FST Falling Edge Hold Time	50	5 X C	A	ns
T _{FTFS}	FST Falling Edge to BCLKT 1 Falling Edge Setup Time	50	(a)	15	ns
T _{BDTD}	BCLKT Rising Edge to Valid PCMT Delay Time	10	G	60	ns
T _{HID}	Delay Time from BCLKT 8 Falling Edge to PCMT Output High Impedance	10	\	60	ns
T _{FRRH}	BCLKR –1 Falling Edge to FSR Rising Edge Hold Time	20			ns
T _{FRRS}	FSR Rising Edge to BCLKR 0 Falling edge Setup Time	80			ns
T _{FRFH}	BCLKR 0 Falling Edge to FSR Falling Edge Hold Time	50			ns
T _{FRFS}	FSR Falling Edge to BCLKR 1 Falling Edge Setup Time	50			ns
T _{DRS}	Valid PCMR to BCLKR Falling Edge Setup Time	0			ns
T _{DRH}	PCMR Hold Time from BCLKR Falling Edge	50			ns

Table 8.2 Short Frame Sync PCM Timing Parameters



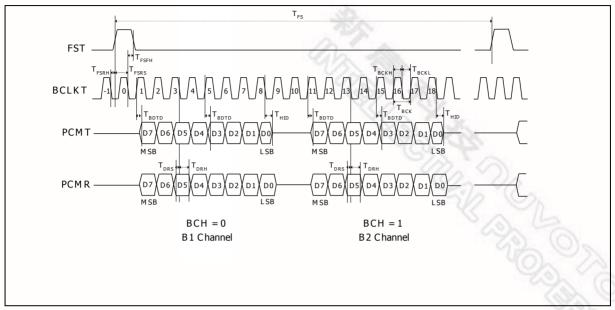


Figure 8.3 IDL PCM Timing

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
1/T _{FS}	FST Frequency		8		kHz
1/T _{BCK}	BCLKT Frequency	256		4096	kHz
T _{BCKH}	BCLKT HIGH Pulse Width	50			ns
T _{BCKL}	BCLKT LOW Pulse Width	50			ns
T _{FSRH}	BCLKT –1 Falling Edge to FST Rising Edge Hold Time	20			ns
T _{FSRS}	FST Rising Edge to BCLKT 0 Falling edge Setup Time	60			ns
T _{FSFH}	BCLKT 0 Falling Edge to FST Falling Edge Hold Time	20			ns
T _{BDTD}	BCLKT Rising Edge to Valid PCMT Delay Time	10		60	ns
T _{HID}	Delay Time from the BCLKT 8 Falling Edge (B1 channel) or BCLKT 18 Falling Edge (B2 Channel) to PCMT Output High Impedance	10		50	ns
T _{DRS}	Valid PCMR to BCLKT Falling Edge Setup Time	20			ns
T _{DRH}	PCMR Hold Time from BCLKT Falling Edge	75			ns

Table 8.3 IDL PCM Timing Parameters

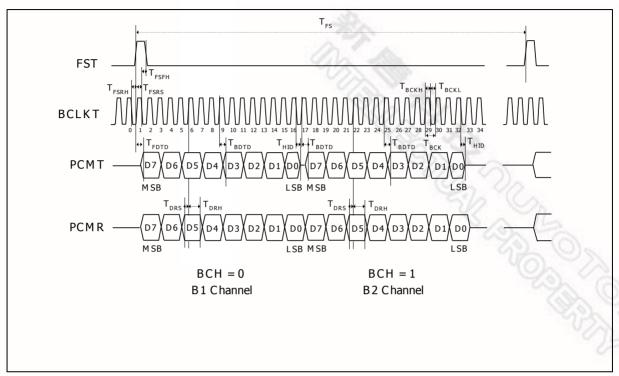


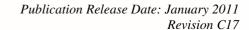
Figure 8.4 GCI PCM Timing

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
1/T _{FST}	FST Frequency		8		kHz
1/T _{BCK}	BCLKT Frequency	512		6176	kHz
T _{BCKH}	BCLKT HIGH Pulse Width	50			ns
T _{BCKL}	BCLKT LOW Pulse Width	50			ns
T _{FSRH}	BCLKT 0 Falling Edge to FST Rising Edge Hold Time	20			ns
T _{FSRS}	FST Rising Edge to BCLKT 1 Falling edge Setup Time	60			ns
T _{FSFH}	BCLKT 1 Falling Edge to FST Falling Edge Hold Time	20			ns
T _{FDTD}	FST Rising Edge to Valid PCMT Delay Time			60	ns
T _{BDTD}	BCLKT Rising Edge to Valid PCMT Delay Time			60	ns
T _{HID}	Delay Time from the BCLKT 16 Falling Edge (B1 channel) or BCLKT 32 Falling Edge (B2 Channel) to PCMT Output High Impedance	10		50	ns
T _{DRS}	Valid PCMR to BCLKT Rising Edge Setup Time	20			ns
T _{DRH}	PCMR Hold Time from BCLKT Rising Edge			60	ns

Table 8.4 GCI PCM Timing Parameters

SYMBOL	DESCRIPTION	MIN	TYP	MAX	UNIT
	2	7	256		
	9	1115 18	512		
			1536		
1/T _{MCK}	Master Clock Frequency	¥, 12	1544		kHz
		11:00	2048		
		70	2560		
			4096)	
T _{MCKH} / T _{MCK}	MCLK Duty Cycle for 256 kHz Operation	45%	Sh.	55%	
Тмскн	Minimum Pulse Width HIGH for MCLK(512 kHz or Higher)	50	'6		ns
T _{MCKL}	Minimum Pulse Width LOW for MCLK (512 kHz or Higher)	50		TO,	ns
T _{FTRHM}	MCLK falling Edge to FST Rising Edge Hold Time	50			ns
T _{FTRSM}	FST Rising Edge to MCLK Falling edge Setup Time	50			ns
T _{RISE}	Rise Time for All Digital Signals			50	ns
T _{FALL}	Fall Time for All Digital Signals			50	ns

Table 8.5 General PCM Timing Parameters





9. ABSOLUTE MAXIMUM RATINGS

9.1. ABSOLUTE MAXIMUM RATINGS

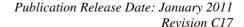
Condition	Value
Junction temperature	150°C
Storage temperature range	-65°C to +150°C
Voltage Applied to any pin	$(V_{SS} - 0.3V)$ to $(V_{DD} + 0.3V)$
Voltage applied to any pin (Input current limited to +/-20 mA)	$(V_{SS} - 1.0V)$ to $(V_{DD} + 1.0V)$
V _{DD} - V _{SS}	-0.5V to +6V

^{1.} Stresses above those listed may cause permanent damage to the device. Exposure to the absolute maximum ratings may affect device reliability. Functional operation is not implied at these conditions.

9.2. OPERATING CONDITIONS

Condition	Value		
Industrial operating temperature	-40°C to +85°C		
Supply voltage (V _{DD})	+4.5V to +5.5V		
Ground voltage (V _{SS})	OV		

<u>Note</u>: Exposure to conditions beyond those listed under Absolute Maximum Ratings may adversely affect the life and reliability of the device.





10. ELECTRICAL CHARACTERISTICS

10.1. GENERAL PARAMETERS

Symbol	Parameters	Conditions	Min ⁽²⁾	Typ ⁽¹⁾	Max (2)	Units
V _{IL}	Input LOW Voltage		<u>ب</u>		0.6	V
V _{IH}	Input HIGH Voltage	120	2.4			V
V _{OL}	PCMT Output LOW Voltage	I _{OL} = 3 mA	120		0.4	V
V _{OH}	PCMT Output HIGH Voltage	$I_{OH} = -3 \text{ mA}$	$V_{DD} - 0.4$)_		V
I _{DD}	V _{DD} Current (Operating) - (ADC + DAC)	No Load	El J	6	8	mA
I _{SB}	V _{DD} Current (Standby)	FST & FSR =V _{ss} ; PUI=V _{DD}	- 63	10	100	μА
I _{pd}	V _{DD} Current (Power Down)	PUI= V _{ss}		0.1	10	μΑ
I _{IL}	Input Leakage Current	V _{SS} <v<sub>IN<v<sub>DD</v<sub></v<sub>		20	+/-10	μА
I _{OL}	PCMT Output Leakage Current	V _{SS} <pcmt<v<sub>DD</pcmt<v<sub>		- 12	+/-10	μА
		High Z State			400	
C _{IN}	Digital Input Capacitance				10	pF
C _{OUT}	PCMT Output Capacitance	PCMT High Z			15	pF

^{1.} Typical values: $T_A = 25$ °C, $V_{DD} = 5.0 V$

^{2.} All min/max limits are guaranteed by Nuvoton via electrical testing or characterization. Not all specifications are 100 percent tested.



10.2. ANALOG SIGNAL LEVEL AND GAIN PARAMETERS

 $V_{DD}\!\!=\!\!5V$ $\pm10\%;$ $V_{SS}\!\!=\!\!0V;$ $T_A\!\!=\!\!-40^{\circ}C$ to $+85^{\circ}C;$ all analog signals referred to $V_{AG};$ MCLK=BCLK= 2.048MHz; FST=FSR=8kHz synchronous operation

PARAMETER	SYM.	CONDITION	TYP.		ISMIT /D)	RECEIVE (D/A)		UNIT
				MIN.	MAX.	MIN.	MAX.	
Absolute Level	L _{ABS}	0 dBm0 = 0dBm @ 600Ω	1.096	2	* 6			V _{PK}
			0.775		3-4	2		V_{RMS}
Max. Transmit Level	T_{XMAX}	3.17 dBm0 for μ-Law	1.579		W	4		V_{PK}
		3.14 dBm0 for A-Law	1.573		-43	- F	%	V_{PK}
Absolute Gain (0 dBm0 @ 1020 Hz; T _A =+25°C)	G _{ABS}	0 dBm0 @ 1020 Hz; 0 -0.25 +0.2 T _A =+25°C +0.2		+0.25	-0.25	+0.25	dB	
Absolute Gain variation	G _{ABST}	$T_A=0$ °C to $T_A=+70$ °C	0	-0.03	+0.03	-0.03	+0.03	dB
with Temperature		$T_A=-40$ °C to $T_A=+85$ °C		-0.05	+0.05	-0.05	+0.05	4
Frequency Response,	G _{RTV}	15 Hz			-40	-0.5	0	dB
Relative to 0dBm0 @ 1020		50 Hz			-30	-0.5	0	
Hz		60 Hz			-26	-0.5	0	
		200 Hz		-1.0	-0.4	-0.5	0	
		300 to 3000 Hz		-0.20	+0.15	-0.20	+0.15	
		3300 Hz		-0.35	+0.15	-0.35	+0.15	
		3400 Hz		-0.8	0	-0.8	0	
		3600 Hz			0		0	
sh.		4000 Hz			-14		-14	
		4600 Hz to 100 kHz			-32		-30	
Gain Variation vs. Level	G_{LT}	+3 to -40 dBm0		-0.3	+0.3	-0.2	+0.2	dB
Tone		-40 to -50 dBm0		-0.6	+0.6	-0.4	+0.4	
(1020 Hz relative to –10 dBm0)		-50 to -55 dBm0		-1.6	+1.6	-1.6	+1.6	
		-21-	Pi	ublication	Release L		uary 2011 vision C17	



10.3. ANALOG DISTORTION AND NOISE PARAMETERS

 $V_{DD}\!\!=\!\!5V$ $\pm10\%;$ $V_{SS}\!\!=\!\!0V;$ $T_A\!\!=\!\!-40^{\circ}C$ to $+85^{\circ}C;$ all analog signals referred to $V_{AG};$ MCLK=BCLK= 2.048MHz; FST=FSR=8kHz synchronous operation

PARAMETER	SYM.	CONDITION	TRA	NSMIT	(A/D)	REC	CEIVE (C)/A)	UNIT
			MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
Total Distortion vs.	$D_{LT\mu}$	+3 dBm0	36	//	D-1	34			dBC
Level Tone (1020 Hz, μ-Law, C-Message		0 dBm0 to -30 dBm0	36		64	36			
Weighted)		-40 dBm0	29		-16	30	2		
,		-45 dBm0	25			25			
Total Distortion vs.	D _{LTA}	+3 dBm0	36			34	D-17		dBp
Level Tone (1020 Hz, A-Law, Psophometric		0 dBm0 to -30 dBm0	36			36	Um'	572	y.
Weighted)		-40 dBm0	29			30	40	× 40	
,		-45 dBm0	25			25	<	DF- 1	2)_
Spurious Out-Of-Band	D _{SPO}	4600 Hz to 7600 Hz						-30	dB
at RO+ (300 Hz to 3400 Hz @ 0dBm0)		7600 Hz to 8400 Hz						-40	5
3400 HZ @ 00BIII0)		8400 Hz to 100000 Hz						-30	
Spurious In-Band (700 Hz to 1100 Hz @ 0dBm0)	D _{SPI}	300 to 3000 Hz			-47			-47	dB
Intermodulation Distortion (300 Hz to 3400 Hz -4 to -21 dBm0	D _{IM}	Two tones			-41			-41	dB
Crosstalk (1020 Hz @ 0dBm0)	D _{XT}				-75			-75	dBm0
Absolute Group Delay	$ au_{ABS}$	1200Hz			360			240	μsec
Group Delay Distortion	τ_{D}	500 Hz			750			750	μsec
(relative to group delay @ 1200 Hz)		600 Hz			380			370	
@ 1200 T12)		1000 Hz			130			120	
1907 180		2600 Hz			130			120	
Children and the		2800 Hz			750			750	
Idle Channel Noise	N _{IDL}	μ-Law; C-message			22			13	dBrnc0
51	2 (A-Law; Psophometric			-68			-78	dBm0p



10.4. ANALOG INPUT AND OUTPUT AMPLIFIER PARAMETERS

 V_{DD} =5V $\pm 10\%$; V_{SS} =0V; T_A =-40°C to +85°C; all analog signals referred to V_{AG} ;

PARAMETER	SYM.	CONDITION	MIN.	TYP.	MAX.	UNIT.
Al Input Offset Voltage	V _{OFF,AI}	Al+, Al-	\$50		±25	mV
Al Input Current	I _{IN,AI}	Al+, Al-	477v	±0.1	±1.0	μА
Al Input Resistance	R _{IN,AI}	AI+, AI- to V _{AG}	10			MΩ
Al Input Capacitance	C _{IN,AI}	Al+, Al-	37-4		10	pF
Al Common Mode Input Voltage Range	V _{CM,AI}	Al+, Al-	1.2	(V)	V _{DD} -1.2	V
Al Common Mode Rejection Ratio	CMRR _{TI}	Al+, Al-	7/	60	5	dB
Al Amp Gain Bandwidth Product	GBW _{TI}	AO, R _{LD} ≥10kΩ		2150		kHz
Al Amp DC Open Loop Gain	GTI	AO, R _{LD} ≥10kΩ		95	(0)	dB
Al Amp Equivalent Input Noise	N _{TI}	C-Message Weighted		-24	h	dBrnC
AO Output Voltage Range	V_{TG}	R_{LD} =10k Ω to V_{AG}	0.5		V _{DD} -0.5	V
		R_{LD} =2k Ω to V_{AG}	1.0		V _{DD} -1.0	
Load Resistance	R _{LDTGRO}	AO, RO to V _{AG}	2		'(kΩ
Load Capacitance	C _{LDTGAO}	AO			100	pF
Load Capacitance	C _{LDTGRO}	RO			500	pF
AO & RO Output Current	I _{OUT1}	0.5 ≤AO,RO+, RO-≤ V _{DD} - 0.5	±1.0			mA
RO+, RO- Output Resistance	R _{RO+, RO-}	RO+, RO-, 0 to 3400 Hz		1		Ω
RO+, RO- Output Offset Voltage	V _{OFF,RO+,RO-}	RO+ to V _{AG} , RO- to V _{AG}			±25	mV
Analog Ground Voltage	V_{AG}	Relative to V _{SS}	2.2	2.4	2.6	V
V _{AG} Output Resistance	R _{VAG}	Within ±25mV change		2.5	12.5	Ω
Power Supply Rejection Ratio (0	PSRR	Transmit	30	80		dBC
to 100 kHz to V _{DD} , C-message)		Receive	30	75		
PAI Input Offset Voltage	V _{OFF,PAI}	PAI			±25	mV
PAI Input Current	I _{IN,PAI}	PAI		±0.05	±1.0	μА
PAI Input Resistance	R _{IN,PAI}	PAI to V _{AG}	10			MΩ
PAI Amp Gain Bandwidth Product	GBW _{PI}	PAO- no load		1000		kHz
Output Offset Voltage	V _{OFF,PO}	PAO+ to PAO-			±50	mV
Load Resistance	R _{LDPO}	PAO+, PAO- differentially	300			Ω
Load Capacitance	C _{LDPO}	PAO+, PAO- differentially			1000	pF
PO Output Current	I _{ОИТРО}	V_{SS} + 0.7 \leq PAO- or PAO+ \leq V_{DD} -0.7	±10.0			mA
PO Output Resistance	R _{PO}	PAO+ to PAO-		1		Ω

PARAMETER	SYM.	CONDITION	MIN.	TYP.	MAX.	UNIT.
PO Differential Gain	G _{PO}	R _{LD} =300Ω, +3dBm0, 1 kHz, PAO+ to PAO-	-0.2	0	+0.2	dB
PO Differential Signal to Distortion	D _{PO}	Z _{LD} =300Ω	45	60		dBC
C-Message weighted		Z_{LD} =100nF + 100 Ω	- XX	40		
		Z_{LD} =100nF + 20 Ω	W	40		
PO Power Supply Rejection Ratio	PSRR _{PO}	0 to 4 kHz	40	55		dB
(0 to 25 kHz to V _{DD} , Differential out)		4 to 25 kHz	4	40		



10.5. DIGITAL I/O

10.5.1. μ-Law Encode Decode Characteristics

Normalized					7/22				Normalized
Encode				Digital	Code				Decode
Decision Levels	D7	D6	D5	D4	D3	D2	D1	D0	Levels
201010	Sign	Chord	Chord	Chord	Step	Step	Step	Step	
8159						9		8	
7903	1	0	0	0	0	0	0	0	8031
:							36		12
4319	1	0	0	0	1	1	1	9	4191
4063								46	
2143	1	0	0	1	1	1	1	1	2079
2015									18 S
1055	1	0	1	0	1	1	1	1	1023
991									:
511	1	0	1	1	1	1	1	1	495
479 :									:
239	1	1	0	0	1	1	1	1	231
223									:
103	1	1	0	1	1	1	1	1	99
95 :									:
35	1	1	1	0	1	1	1	1	33
31 :									:
3	1	1	1	1	1	1	1	0	2
101	55.1	1	1	1	1	1	1	1	0
0	F								

Notes:

Sign bit = 0 for negative values, sign bit = 1 for positive values



10.5.2. A-Law Encode Decode Characteristics

Normalized				Digital	Code				Normalized
Encode	D7	D6	D5	D4	D3	D2	D1	D0	Decode
Decision Levels	Sign	Chord	Chord	Chord	Step	Step	Step	Step	Levels
4096	1	0	1	0	1	0	777	0	4032
3968	'		'	0			D.	(A)	:
2176	1	0	1	0	0	1	0	40	2112
2048							77	0	4
1088	1	0	1	1	0	1	0	1/2	1056
1024								6	D. (
544	1	0	0	0	0	1	0	1	528
512 :									(0)
272	1	0	0	1	0	1	0	1	264
256									:
136	1	1	1	0	0	1	0	1	132
128 :									:
68	1	1	1	1	0	1	0	1	66
64									:
2	1	1	0	1	0	1	0	1	1
0									

Notes:

- 1. Sign bit = 0 for negative values, sign bit = 1 for positive values
- 2. Digital code includes inversion of all even number bits

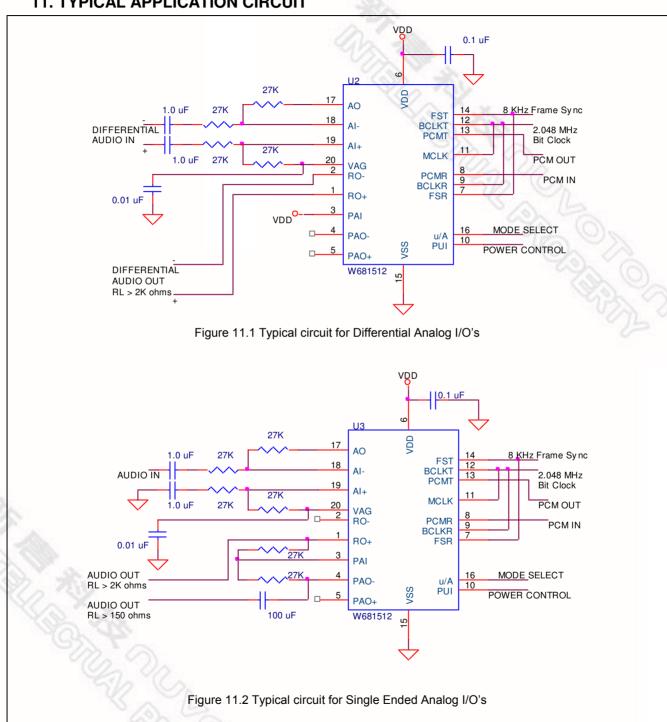
10.5.3. PCM Codes for Zero and Full Scale

		μ-Law		A-Law			
Level	Sign bit	Chord bits	Step bits	Sign bit	Chord bits	Step bits	
	(D7)	(D6,D5,D4)	(D3,D2,D1,D0)	(D7)	(D6,D5,D4)	(D3,D2,D1,D0)	
+ Full Scale	1	000	0000		010	1010	
+ Zero	1	111	1111	1/07	101	0101	
- Zero	0	111	1111	0	101	0101	
- Full Scale	0	000	0000	0	010	1010	

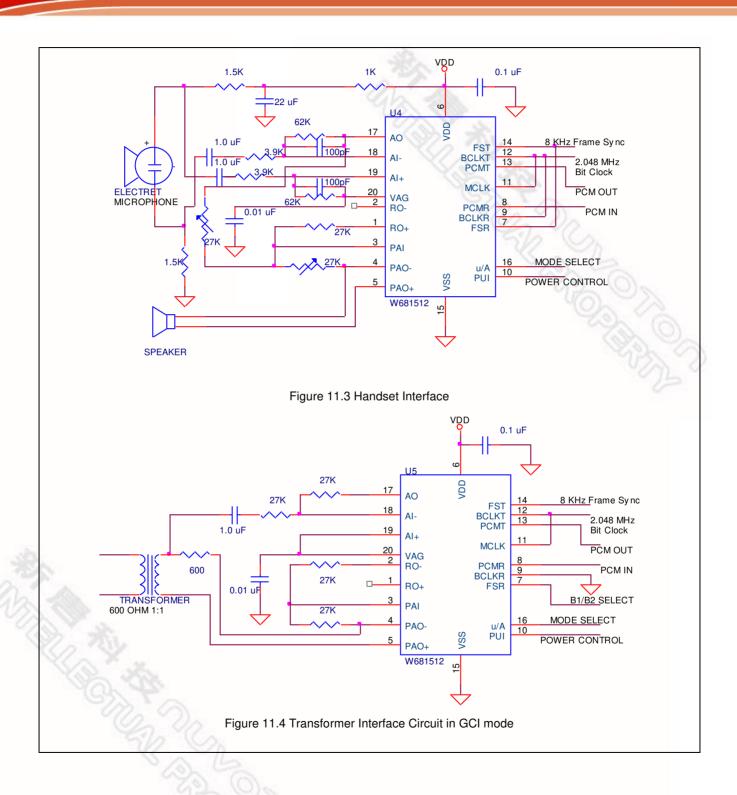
10.5.4. PCM Codes for 0dBm0 Output

		μ-Law		A-Law				
Sample	Sign bit	Chord bits	Step bits	Sign bit	Chord bits	Step bits		
	(D7)	(D6,D5,D4)	(D3,D2,D1,D0)	(D7)	(D6,D5,D4)	(D3,D2,D1,D0)		
1	0	001	1110	0	011	0100		
2	0	000	1011	0	010	0001		
3	0	000	1011	0	010	0001		
4	0	001	1110	0	011	0100		
5	1	001	1110	1	011	0100		
6	1	000	1011	1	010	0001		
7	1	000	1011	1	010	0001		
8	1	001	1110	1	011	0100		

11. TYPICAL APPLICATION CIRCUIT

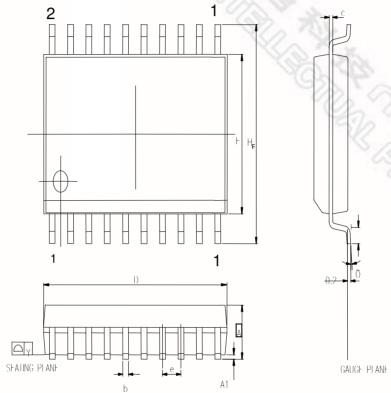


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12. PACKAGE SPECIFICATION

12.1. 20L SOG (SOP)-300MIL

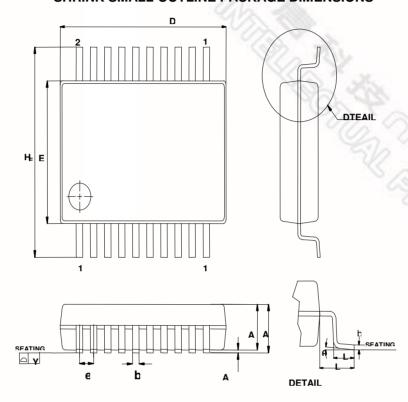


SMALL OUTLINE PACKAGE (SAME AS SOG & SOIC) DIMENSIONS

	DIMENS	ION (MM)	DIMEN	SION (INCH)
SYMBOL	MIN.	MAX.	MIN.	MAX.
Α	2.35	2.65	0.093	0.104
A1	0.10	0.30	0.004	0.012
b	0.33	0.51	0.013	0.020
С	0.23	0.32	0.009	0.013
Е	7.40	7.60	0.291	0.299
D	12.60	13.00	0.496	0.512
е	1.27	BSC	0.0	50 BSC
HE	10.00	10.65	0.394	0.419
Υ	-	0.10	-	0.004
D F	0.40	1.27	0.016	0.050
θ	0º	8º	Oº	8º

12.2. 20L SSOP-209 MIL

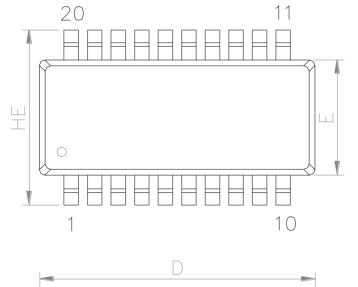
SHRINK SMALL OUTLINE PACKAGE DIMENSIONS

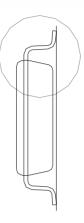


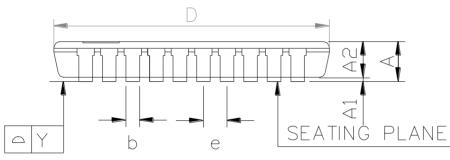
	DI	MENSION (I	MM)	DI	MENSION (IN	ICH)
SYMBOL	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
Α	-	-	2.00	-	-	0.079
A1	0.05	-	-	0.002	-	-
A2	1.65	1.75	1.85	0.065	0.069	-
b	0.22	-	0.38	0.009	-	0.015
С	0.09	-	0.25	0.004	-	0.010
D	6.90	7.20	7.50	0.272	0.283	0.295
E	5.00	5.30	5.60	0.197	0.209	0.220
H _E	7.40	7.80	8.20	0.291	0.307	0.323
е	-	0.65	-	-	0.0256	-
20 L X	0.55	0.75	0.95	0.021	0.030	0.037
(L1)	71-	1.25	-	-	0.050	-
Y	100	-	0.10	-	-	0.004
0	0º	27 -	8º	0	-	8º

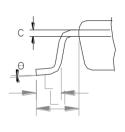
12.3. 20L TSSOP - 4.4X6.5MM

PLASTIC THIN SHRINK SMALL OUTLINE PACKAGE (TSSOP) DIMENSIONS





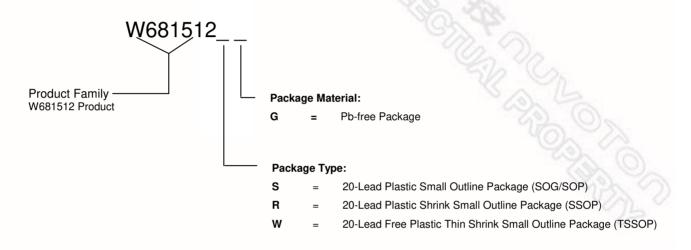




SYMBOL	DIMENSION (MM)			DIMENSION (INCH)		
	MIN.	N□M.	MAX.	MIN.	N□M.	MAX.
Α	-	-	1,20	-	-	0.047
A1	0,05	-	0,15	0.002	-	0.006
A2	0.80	0.90	1,05	0.031	0.035	0.041
Ε	4.30	4.40	4.50	0.169	0.173	0.177
HE	6.40 BSC			0.252 BSC		
D	6.40	6.50	6.60	0.252	0.256	0.260
L	0.50	0.60	0.75	0.020	0.024	0.030
L1	1.00 REF			0.039 REF		
b	0.19	-	0.30	0.007	-	0.012
е	0.65 BSC			0.059 B2C		
С	0.09	-	0.20	0.004	-	0.008
Θ	0,	-	8°	0.	-	8°
Υ	0.10 BASIC			0.004 BASIC		

13. ORDERING INFORMATION

Nuvoton Part Number Description



When ordering W681512 series devices, please refer to the following part numbers.

Part Number	
W681512SG	
W681512RG	
W681512WG	



14. VERSION HISTORY

VERSION	DATE	PAGE	DESCRIPTION	
C14 April, 2007		31	SOP Package diagram legible	
		33	SSOP Package diagram legible	
		35	TSSOP Package diagram legible	
		36	Removed Pb TSSOP Package	
		36	Footnote on Pb parts limited availability	
C15	November, 2007	2	Removed all Pb packages	
		8	Improved Figure 7.1 block diagram (AO Output)	
		21	Corrected VDD current parameters (ADC+DAC)	
		21	Corrected IOH condition.	
		24	Corrected output voltage condition	
		27	Corrected 64 to 68 digital code D4 to 1.	
		27	Corrected encode decision levels from 2048 to 2176	
040	Jannuary 2009	22	Idle Channel Noise (μ-Law; C-message) value updated	
C16		33	Leaded packages no longer supported	
C17	Jannuary 2010	32	Improved TSSOP package diagram	

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